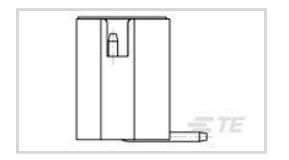
1775317-8 - ACTIVE

HPI

TE Internal #: 1775317-8 PCB Mount Header, Vertical, Wire-to-Board, 8 Position, .098 in [2.5 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Signal, Natural, HPI

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 2.5MM HEADERS



Connector System: Wire-to-Board

Number of Positions: 8

Number of Rows: 1

Centerline (Pitch): 2.5 mm [.098 in]

PCB Mount Orientation: Vertical

All AMP HPI 2.5MM HEADERS (78)

Features

Product Type Features

Connector System

Header Type

Wire-to-Board

Fully Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Connector Contact Load Condition	Fully Loaded
Number of Positions	8
Number of Rows	1
PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
Contact Layout	Inline

PCB Mount Header, Vertical, Wire-to-Board, 8 Position, .098 in [2.5 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Signal, Natural, HPI



Contact Mating Area Length	3.5 mm[.138 in]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2 µm[80 µin]
Contact Mating Area Plating Material Thickness	2 µm[80 µin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Matte
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Brass
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Terminations per Post (Max)	3

Termination Post & Tail Length

Termination Method to Printed Circuit Board

Surface Mount

2 mm[.079 in]

Mechanical Attachment

Mating Alignment Type	Polarization
Mating Retention	Without
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	PA 9T GF
Centerline (Pitch)	2.5 mm[.098 in]
Dimensions	
Connector Length	24.5 mm[.965 in]
Connector Height	6.4 mm[.252 in]
Connector Width	4.8 mm[.189 in]
PCB Thickness (Recommended)	.8 mm[.031 – .063 in]

PCB Mount Header, Vertical, Wire-to-Board, 8 Position, .098 in [2.5 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Signal, Natural, HPI



Usage Conditions

Operating Temperature Range	-25 – 85 °C[-13 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	500
Packaging Type	Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUN 2013

Candidate List Declared Against: JUN 2013 (144) SVHC > Threshold: Not Yet Reviewed

Not Low Halogen - contains Br or Cl > 900 ppm.

Wave solder capable to 265°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

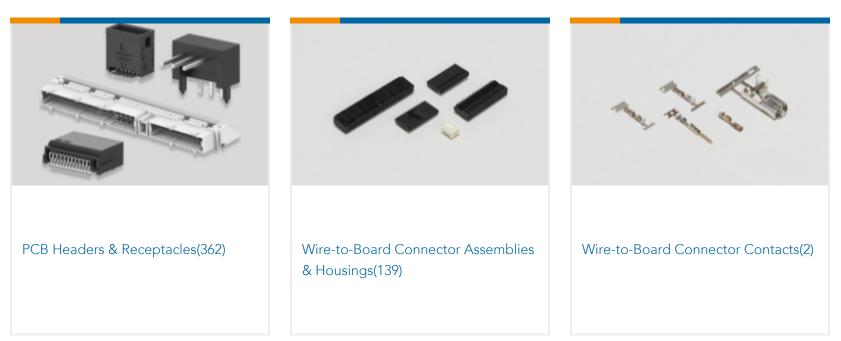
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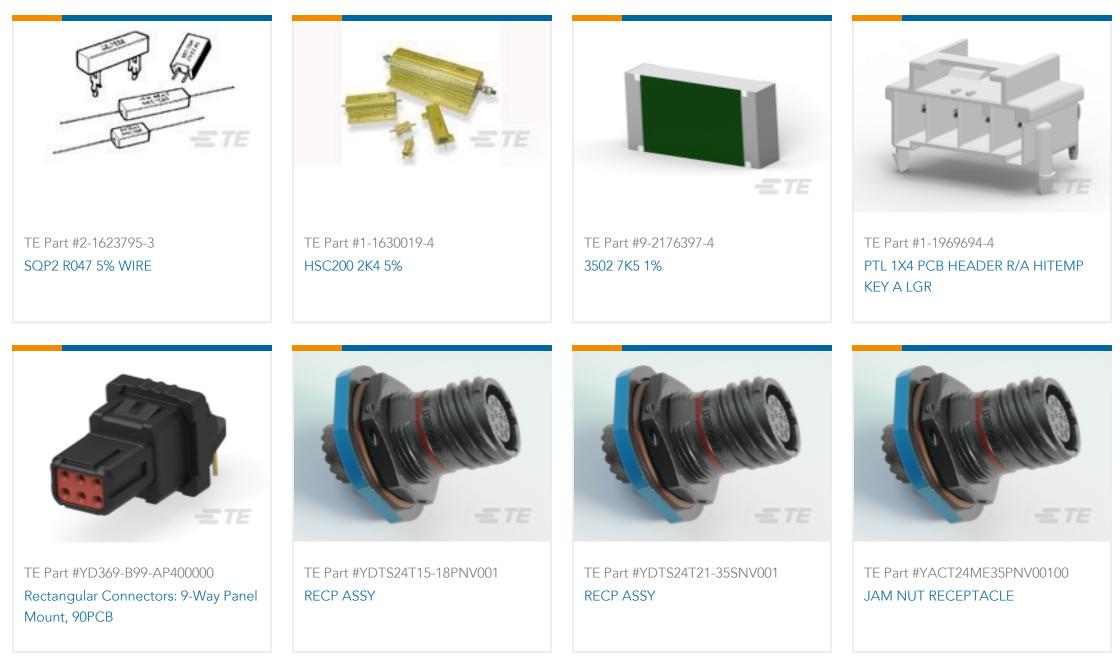
Compatible Parts



Also in the Series | HPI



Customers Also Bought



Documents

Product Drawings HPI.,2.5MM PITCH,V/T,SMT TYPE,8 POS

English

CAD Files

S For support call+1 800 522 6752

PCB Mount Header, Vertical, Wire-to-Board, 8 Position, .098 in [2.5 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Signal, Natural, HPI



3D PDF

3D

Customer View Model ENG_CVM_CVM_1775317-8_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1775317-8_A.3d_igs.zip

English

Customer View Model ENG_CVM_CVM_1775317-8_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages HPI Connectors QRG

English

Product Specifications

AMP 2.5MM PITCH HPI WIRE TO BOARD SYSTEM.

English

Application Specification

English

Agency Approvals UL Report

English